

Powering Next-Gen AI: JPC Powers NVIDIA Vera Rubin Architecture at Scale



100A AC Whip cable

Powering AI Infrastructure at Scale: JPC in the NVIDIA AI Factory MGX™ Ecosystem

As AI data centers scale at an unprecedented pace, reliable high-power connectivity has become mission-critical. At Computex 2026, JPC Connectivity is showcasing advanced power solutions designed for the **NVIDIA MGX™ platform**—the modular architecture powering today’s AI factories.

The NVIDIA MGX™ platform enables faster, more flexible AI system design by integrating standardized components such as GPUs, CPUs, power, cooling, and networking. Its latest generation, built on the **Vera Rubin platform**, introduces some of the most power-dense AI rack systems ever deployed—demanding consistent, high-current delivery at production scale.

JPC plays a critical role in enabling Vera Rubin full production readiness. From early-stage design collaboration to volume manufacturing, JPC’s high-current cabling solutions are engineered to meet stringent electrical, thermal, and space requirements—ensuring stable and efficient power delivery across large-scale AI deployments.

Key solutions include:

- **60A Power Whip (GB200 NVL72/ GB300 NVL72 platform)** – ORV3-compliant, UL817 certified, with flexible lengths for seamless rack integration
- **100A Power Whip (Vera Rubin platform)** – engineered for next-generation AI workloads, delivering sustained high-current performance, superior routing flexibility, and readiness for global deployment
- **Busbar Solutions for Vera Rubin platform** – supporting high-density power architectures with ORV3, 72kW (HPRv2), and 90kW+ designs operating at 54V DC with currents up to 200A, enabling efficient power distribution for next-generation AI racks
- **Comprehensive ORV3 power portfolio & prototyping** – including AC whip assemblies and rapid prototyping capabilities, helping customers accelerate from validation to full-scale production

With over 30 years of experience and deep engineering expertise, JPC is a key enabler in bringing next-generation AI infrastructure from concept to deployment.

Visit JPC at COMPUTEX 2026 – Booth J0410, TaiNEX 1 (1F) to learn more.

JPC connectivity

 **COMPUTEX**
TAIPEI

JUNE **2-4** 09:30-17:30 JUNE **5** 09:30-16:30

BOOTH

J0410 Nangang Exhibition Center, Hall 1, 1F



Corporate Communications

Weiling Yi

weiling_yi@jpcco.com